# INTEGRATED CIRCUITS



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### **TDA8780M**

### FEATURES

- 72 dB true logarithmic dynamic range
- Small-signal gain-adjustment facility
- Constant limiting output voltage
- Temperature and DC power supply voltage independent
- Easy interfacing to analog-to-digital converters
- Output DC level shift facility.

#### **APPLICATIONS**

- Dynamic range compression
- IF signal dynamic range reduction in digital receivers
- Compression receivers.

### **GENERAL DESCRIPTION**

The TDA8780M is a true logarithmic amplifier intended for dynamic range reduction of IF signals at 10.7 MHz in digital radio receivers. It offers true logarithmic characteristics over a 72 dB input dynamic range, has a small-signal gain-adjustment facility and a constant limiting output voltage for large input levels.

### QUICK REFERENCE DATA

A unique feature is the smooth "changeover" from linear operation (inputs less than  $60 \mu$ V) to logarithmic mode.

The device is manufactured in an advanced BiCMOS process which enables high performance being obtained with low DC power supply consumption. The true logarithmic amplifier can be driven by single-ended or differential inputs. The DC operating point is set by overall on-chip feedback decoupled by two off-chip capacitors, which define the low-frequency cut-off point.

The performance of the amplifier is stabilized against temperature and DC power supply variations. The differential output is converted internally to a single-ended output by an on-chip operational amplifier arrangement in which the DC output level is set by an externally-supplied reference voltage. A power-down facility allows the circuit to be disabled from a control input.

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V <sub>P</sub>	supply voltage	4.5	5.0	5.5	V
l <sub>P</sub>	supply current	_	-	6.7	mA
I <sub>P(PD)</sub>	supply current in power-down mode	-	-	250	μA
f <sub>in</sub>	operating input frequency	-	-	15	MHz
V <sub>in(M)</sub>	dynamic logarithmic input voltage (peak value)	0.06	-	300	mV
T <sub>amb</sub>	operating ambient temperature	-20	-	+75	°C

### **ORDERING INFORMATION**

TYPE NUMBER		PACKAGE				
ITPE NUMBER	NAME	DESCRIPTION	VERSION			
TDA8780M     SSOP20     plastic shrink small outline package; 20 leads; body width 4.4 mm     S		SOT266-1				

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### **BLOCK DIAGRAM**



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### PINNING

SYMBOL	PIN	DESCRIPTION
Vin	1	signal voltage input
GND1	2	ground 1
C <sub>DEC1</sub>	3	control circuit first decoupling and optional start-up capacitor connection
R <sub>g</sub>	4	small-signal gain-setting resistor
R <sub>g</sub>	5	small-signal complementary gain-setting resistor
C <sub>lf</sub>	6	low-frequency cut-off point setting capacitor
GND2	7	ground 2
V <sub>ref</sub>	8	external reference voltage input
n.c.	9	not connected
GND3	10	ground 3 (main ground)
V <sub>P</sub>	11	power supply
n.c.	12	not connected
V <sub>out</sub>	13	true logarithmic voltage output
GND4	14	ground 4
¯C <sub>lf</sub>	15	complementary low-frequency cut-off point setting capacitor
CE	16	TTL-level-compatible circuit enable input (active HIGH)
TEST	17	test input; connected to ground in normal operation
C <sub>DEC2</sub>	18	control circuit second decoupling and optional start-up capacitor
GND5	19	ground 5
$\overline{V}_{in}$	20	complementary signal voltage input



#### FUNCTIONAL DESCRIPTION

A true logarithmic amplifier can be realized from a cascade of similar stages each stage consisting of a pair of amplifiers whose inputs and outputs are connected in parallel. One of these amplifiers can be formed by an undegenerated long-tailed pair which provides high gain but limited linear input signal-handling capability. The other amplifier can be formed by a degenerated long-tailed pair which provides a gain of unity and a much larger linear input signal-handling capability.

The overall cascade amplifies very small input signals but, once these reach the level at which the undegenerated long-tailed pair in the last stage is at the limit of its linear signal-handling capability, the output voltage becomes logarithmically dependent on the input signal level. This behaviour continues until the input signal reaches the level at which undegenerated long-tailed pair in the first stage is at the limit of its linear input signal-handling capability. The transfer characteristic beyond this point then depends on the exact configuration of the degenerated long-tailed pair in the first stage.

Five stages are used in the TDA8780M to provide a 72 dB true logarithmic dynamic range. The DC bias current in the undegenerated long-tailed pair in the first stage is made externally adjustable, using an off-chip resistor, to provide a small-signal gain adjustment facility. The small signal gain defined by this resistor is valid when the IC is operating in the "linear" mode, for input signals typically less than 60  $\mu$ V.

A high-level limiter is inserted between the first and second stages to provide a constant limiting output voltage which is essentially independent of the value of the gain setting resistor. These stages can be driven by single-ended or differential inputs. The DC operating point is set by overall on-chip feedback decoupled by two off-chip capacitors which define the low-frequency cut-off point. The performance is stabilized against temperature and DC power supply variations. The input to the true logarithmic amplifier is protected against damage due to excessive differential input signals by diodes.

The differential output from the true logarithmic amplifier is converted internally to a single-ended output by an on-chip operational amplifier arrangement in which the DC output level is set by an externally-supplied reference voltage. The output is capable of driving loads down to 10 k $\Omega$ . The limiting output voltage and the output drive capability have been chosen to facilitate interfacing to analog-to-digital converters. A major part of the DC power supply current consumption of the device is associated with provision of this output drive capability. The DC power supply consumption is significantly less when the device is driving smaller loads.

A power-down facility allows the circuit to be disabled from a TTL-level compatible control input.

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#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER		MAX.	UNIT
VP	supply voltage		+6.0	V
Vi	input voltage all other pins referenced to ground	-0.3	V <sub>P</sub> + 0.3	V
T <sub>amb</sub>	operating ambient temperature	-20	+75	°C
T <sub>stg</sub>	IC storage temperature	-55	+150	°C

#### HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be totally safe, it is desirable to take normal precautions appropriate to handling MOS devices.

ESD in accordance with "MIL STD 883C" - "Method 3015".

#### CHARACTERISTICS

 $V_P = 5 \text{ V}$ ;  $T_{amb} = 25 \text{ °C}$ ;  $V_{ref} = 2.5 \text{ V}$ ;  $V_{in}$  at  $f_{in} = 10.7 \text{ MHz}$ ;  $R_g = 3.3 \text{ k}\Omega$ ; output not loaded; unless otherwise specified. Signal values expressed as peak voltages mV (peak),  $\mu$ V (peak) or dBm (50  $\Omega$ ).

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply				•	•	
VP	supply voltage		4.5	5.0	5.5	V
I <sub>P</sub>	supply current	V <sub>P</sub> = 5.5 V; V <sub>in</sub> = 1 V	-	5.4	6.7	mA
		V <sub>P</sub> = 5.0 V; V <sub>in</sub> = 1 V	-	4.9	6.2	mA
I <sub>P(PD)</sub>	supply current in power-down	output not loaded	-	40	200	μA
		$R_{L} = 10 \text{ k}\Omega$	-	100	250	μΑ
t <sub>sw</sub>	switching time	see Fig.6	_	70	-	μs
Reference	e input (pin 8)					
V <sub>ref</sub>	external reference voltage input		2.0	2.5	V <sub>P</sub> - 2.0	V
R <sub>ref</sub>	external reference resistance input		-	40	-	kΩ
Inputs (pi	ns 1 and 20)					
f <sub>in</sub>	input operating frequency	note 1	1.0	10.7	15	MHz
R <sub>diff</sub>	differential small-signal input resistance	V <sub>in</sub> = 10 mV	-	10	-	kΩ
C <sub>diff</sub>	differential input capacitance		-	2	-	pF
V <sub>in(min)</sub>	input voltage level at start of logarithmic characteristic		-	60	-	μV
V <sub>in(top)</sub>	input voltage level at top end of logarithmic characteristic		-	300	_	mV
V <sub>in(max)</sub>	maximum input signal voltage	input protection diodes not conducting	-	1	-	V
$\Delta V_{in}$	input voltage level spread across logarithmic range	over whole $T_{amb}$ and $V_P$ range	-	±2.5	-	dB

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Output (p	in 13)		-1	1	1	1
Vos	DC offset voltage (Vout to Vref)	no input signal	-60	+40	+140	mV
V <sub>out</sub>	output voltage level across	$V_{in} = 60 \ \mu V \ (-71.4 \ dBm)$	45	80	115	mV
	logarithmic range	$V_{in} = 400 \ \mu V \ (-54.9 \ dBm)$	200	245	290	mV
		V <sub>in</sub> = 3 mV (–37.4 dBm)	365	440	495	mV
		V <sub>in</sub> = 25 mV (–19.0 dBm)	530	610	690	mV
		V <sub>in</sub> = 200 mV (–1.0 dBm)	680	780	880	mV
		V <sub>in</sub> = 300 mV (+2.6 dBm)	710	820	930	mV
		$R_{g} = 0; V_{in} = 3 \text{ mV}; \text{ see Fig.} 3$	_	530	-	mV
		$R_g = \infty$ ; $V_{in} = 3 \text{ mV}$ ; see Fig.3	_	360	-	mV
V <sub>out(lim)</sub>	limiting output voltage	V <sub>in</sub> = 1 V (+13.0 dBm)	750	950	1050	mV
Δφ	spread in output phase transfer characteristic across logarithmic range		-	15	-	
f <sub>lf</sub>	low frequency cut-off point (3 dB)	see Fig.6	_	-	0.1	MHz
G <sub>flat</sub>	gain flatness at 1 to 15 MHz	V <sub>in</sub> = 10 mV	_	0.5	1.5	dB
R <sub>13</sub>	output resistance		_	150	-	Ω
Logic inp	ut (pin 16)		•	•	•	•
VIL	LOW level input voltage		0	-	0.8	V
V <sub>IH</sub>	HIGH level input voltage		2	-	V <sub>P</sub>	V
ILI	input leakage current	$V_{IL} = 0$ to $V_P$	_1	_	+1	μA

Note

1. With some changes in application the lower input frequency limit can be lowered.

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#### **APPLICATION INFORMATION**

The circuit is typically connected as shown in Fig.6. The single-ended 10.7 MHz input IF signal is applied (arbitrarily) to one of the two input pins via a ceramic filter. These inputs should not be DC coupled as this will disable the on-chip feedback which sets the DC operating point of the true logarithmic amplifier. The relatively high impedance of these inputs facilitates correct termination of the ceramic filter by an off-chip resistor.

The low-frequency cut-off point is determined by the value of capacitors connected to pins 6 and 15 which decouple the overall DC feedback and the value of the input coupling capacitors. The output is coupled to an analog-to-digital converter thus the value of the voltage fed to the reference voltage input is not critical. It could be useful in other applications, where the output may be DC coupled to an alternative analog-to-digital converter, to derive this reference voltage from the centre of the input resistor chain of the analog-to-digital converter.



#### PACKAGE OUTLINE



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### TDA8780M

### SOLDERING

### Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

#### **Reflow soldering**

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

### Wave soldering

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

#### **Repairing soldered joints**

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

### TDA8780M

### DEFINITIONS

Data sheet status				
Dbjective specification     This data sheet contains target or goal specifications for product development.				
Preliminary specification	Preliminary specification This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
Limiting values				
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.				
Application information				
Where application information is given, it is advisory and does not form part of the specification.				

#### LIFE SUPPORT APPLICATIONS

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